



NEXX Systems Announces Electroplating Process & Equipment Development Collaboration for Advanced Semiconductor Packaging

Billerica, MA – March 9, 2009 NEXX Systems today announced a multi-year joint development program with IBM on advanced semiconductor chip packaging and integration. In the program, IBM and NEXX will collaborate in New York State on the development of electroplating hardware and processes for advanced chip packaging applications.

The next generation of 3D semiconductor packages, with shrinking form factors, stacking, increasing power management demands, and complex packaging schemes, pose many challenges that need to be addressed. This new collaboration will focus on meeting IBM's and its semiconductor research and development alliance partners' requirements in electroplating for chip interconnections and 3D packaging. The program will build on IBM's packaging expertise and the unique capabilities of the NEXX Stratus electroplating tool. The Stratus was selected for this program due to its low cost of ownership, excellent process performance, development capability, and extendibility to future applications.

"The IBM packaging team has long benefited from the flexibility and extendability of its existing C4NP and electroplating C4 processes for a wide range of materials for traditional first-level two-dimensional packaging," said Jean Trehwella, IBM Director of Packaging Research and Development. "We are pleased to share a vision with the NEXX team that there are additional electroplating options that will broaden the flexibility of our electroplating materials as we develop new interconnections for 3D and other advanced packaging applications."

Tom Walsh, NEXX CEO, added, "NEXX is very excited to have the opportunity to work with IBM as a joint development partner. IBM's extensive experience in electroplated C4 and C4NP process technology is unique in the industry. This program will provide a basis to expand the capability of the NEXX Stratus to meet industry needs for electroplating processes delivered on a qualified manufacturing tool."

About NEXX: NEXX Systems, a leading provider of processing equipment for advanced wafer-level packaging applications, brings exceptional technical expertise to the flip chip and advanced packaging markets. Our product lines provide the most efficient, yet affordable, systems of their kind: Stratus for high throughput electroplating of metals, and Apollo and Nimbus for multi-layer sputter deposition of metals. Additional information can be found at: www.nexxsystems.com.